

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/02/2022

Details for "LMV651MF/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LMV651MF/NOPB	SN	Level-1-260C-UNLIM	Texas Instruments Electronics	DBV 5	2.9 x 1.6 x 1.45	18

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.01761	100	1000000	0.097781	978
Sub-Total			0.01761	100	1000000	0.097781	978
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.025987	75.000722	750007	0.144296	1443
Thermoplastics	Epoxy	85954-11-6	0.008662	24.999278	249993	0.048097	481
Sub-Total			0.034649	100	1000000	0.192392	1924
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	5.436408	96.509995	965100	30.186234	301862
Copper and Its Alloys	Iron	7439-89-6	0.134065	2.379993	23800	0.74441	7444
Copper and Its Alloys	Phosphorus	7723-14-0	0.00169	0.030002	300	0.009384	94
Precious Metals	Silver	7440-22-4	0.054077	0.960004	9600	0.300268	3003
Zinc and Its Alloys	Zinc	7440-66-6	0.00676	0.120007	1200	0.037536	375
Sub-Total			5.633	100	1000000	31.277832	312778
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.7	100	1000000	3.886825	38868
Sub-Total			0.7	100	1000000	3.886825	38868
Mold Compound							
Other Inorganic Materials	Silica	7631-86-9	10.20686	88.699994	887000	56.674677	566747
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	0.345215	2.999999	30000	1.916843	19168
Other Plastics and Rubber	Carbon Black	1333-86-4	0.034522	0.300004	3000	0.191687	1917
Thermoplastics	Epoxy	85954-11-6	0.920574	8.000003	80000	5.111585	51116
Sub-Total			11.507171	100	1000000	63.894793	638948
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.11713	100	1000000	0.650377	6504
Sub-Total			0.11713	100	1000000	0.650377	6504
Total			18.00956			100	1000000

Important Note
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMISs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.